IN THE CLAIMS:

Please amend the claims as follows:

1. (Currently Amended) A laser-markable ~~tape~~ structure for marking a semiconductor device comprising:

a tape comprising a flexible film material; and

a multilayer adhesive including:

a first outermost adhesive layer comprising a mixture of electromagnetic radiation-curable components, ~~said~~ the electromagnetic radiation-curable components providing a laser-markable surface upon exposure to an electromagnetic radiation source; and

a second adhesive layer disposed between ~~said~~ the tape and ~~said~~ the first outermost adhesive layer.

2. (Currently Amended) The laser-markable ~~tape~~ structure of claim 1, wherein ~~said~~ the laser-markable ~~tape~~ structure is adhered to at least a portion of a surface of a bare semiconductor die, the first outermost adhesive layer being disposed adjacent the surface of the bare semiconductor die.

3. (Currently Amended) The laser-markable ~~tape~~ structure of claim 2, wherein ~~said laser-markable tape is adhered to a~~ the at least a portion of the surface of a bare semiconductor die ~~surface subjected to a backgrinding process~~ has grinding marks therein.

4. (Currently Amended) The laser-markable ~~tape~~ structure of claim 2, wherein ~~said~~ the first outermost adhesive layer is ~~cured upon exposure to said electromagnetic radiation source to thereby attach said first outermost adhesive layer~~ permanently attached to ~~said~~ the at least a portion of ~~said~~ the surface of ~~said~~ the bare semiconductor die when the radiation-curable components are in a cured state.

5. (Currently Amended) The laser-markable ~~tape~~ structure of claim 4, wherein ~~said~~the ~~curing of said first outermost adhesive layer results in a loss of adhesion between said first outermost adhesive layer and said second adhesive layer~~ laser-markable structure including a first bond strength between the tape and the at least a portion of the surface of the bare semiconductor die when the electromagnetic radiation-curable components are in an uncured state, and a second bond strength between the tape and the first outermost adhesive layer when the electromagnetic radiation-curable components are in a cured state, the second bond strength being lower than the first bond strength.

6. (Currently Amended) The laser-markable ~~tape~~ structure of claim 4, wherein ~~said curing of said first outermost adhesive layer forms~~ the laser-markable surface includes a substantially homogenous surface disposed over ~~said~~ the at least a portion of ~~said~~ the surface of ~~said~~ the bare semiconductor die, the laser-markable surface being suitable for laser marking.

7. (Currently Amended) The laser-markable ~~tape~~ structure of claim 3, wherein ~~said~~ the second adhesive layer ~~is cured by exposure to an electromagnetic radiation source~~ comprises radiation-curable components.

8. (Currently Amended) The laser-markable ~~tape~~ structure of claim 1, wherein ~~said~~ the tape comprises a flexible film material having translucent properties.

9. (Currently Amended) A tape for use in the laser marking of a semiconductor device comprising:

a flexible film material; and

a multilayer adhesive including:

a first outermost adhesive layer comprising a mixture of electromagnetic radiation-curable components for providing a mark on a laser-markable surface upon exposure thereof to electromagnetic radiation; and

a second adhesive layer disposed between ~~said~~ the flexible film material and ~~said~~ the first outermost adhesive layer.

10. (Currently Amended) The tape of claim 9, wherein ~~said tape includes a tape~~ the multilayer adhesive has a level of adhesiveness suitable for adhering the tape to at least a portion of a surface of a bare semiconductor die.

11. (Currently Amended) The tape of claim 10, wherein ~~said tape includes a tape for adhering to said~~ the portion of ~~said~~ the surface of ~~said~~ the bare semiconductor die ~~after backgrinding of said portion of said surface of said bare semiconductor die~~ has grinding marks therein.

12. (Currently Amended) The tape of claim 10, wherein ~~said~~ the first outermost adhesive layer ~~includes a first outermost adhesive layer for curing upon exposure to a source of electromagnetic radiation for attaching said first outermost adhesive layer~~ is permanently attached to ~~said~~ the at least a portion of ~~said~~ the surface of ~~said~~ the bare semiconductor die when the radiation-curable components are in a cured state.

13. (Currently Amended) The tape of claim 12, wherein ~~said~~ the second adhesive layer comprises radiation-sensitive components, the second adhesive layer comprising a first level of adhesiveness when the radiation-curable components of ~~curing of said~~ the first outermost adhesive layer are in an uncured state, and a second level of adhesiveness ~~provides a loss of adhesion between~~ when the radiation-curable components of ~~said~~ the first outermost adhesive layer ~~and said second adhesive layer~~ are in a cured state, the second level of adhesiveness being lower than the first level of adhesiveness.

14. (Currently Amended) The tape of claim 12, wherein ~~said curing of said first outermost adhesive layer forms~~ the laser-markable surface comprises a substantially homogenous

surface disposed over ~~said~~ the at least a portion of ~~said~~ the surface of ~~said~~ the bare semiconductor die suitable for providing a mark by laser marking.

15. (Currently Amended) The tape of claim 11, wherein ~~said~~ the second adhesive layer ~~is cured by exposure to electromagnetic radiation~~ comprises radiation-curable components.

16. (Currently Amended) The tape of claim 9, wherein ~~said~~ the flexible film material comprises a flexible film material having translucent properties.

17. (Currently Amended) A tape for use in the marking of a semiconductor device comprising:

film material; and

at least two layers of adhesive including:

a first outermost adhesive layer comprising a mixture of electromagnetic radiation-curable components for providing a mark on a surface upon exposure thereof to electromagnetic radiation; and

a second adhesive layer disposed between ~~said~~ the film material and ~~said~~ the first outermost adhesive layer.

18. (Currently Amended) The tape of claim 17, wherein ~~said tape includes a tape~~ the first outermost adhesive layer has a level of adhesiveness suitable for adhering the tape to at least a portion of a surface of a bare semiconductor die.

19. (Currently Amended) The tape of claim 18, wherein ~~said tape includes a tape for adhering to said~~ the portion of ~~said~~ the surface of ~~said~~ the bare semiconductor die ~~after a backgrinding process~~ has grinding marks therein.

20. (Currently Amended) The tape of claim 18, wherein ~~said~~ the first outermost adhesive layer ~~includes a first outermost adhesive layer for curing upon exposure to~~

~~electromagnetic radiation for attaching said first outermost adhesive layer~~ is permanently attached to ~~said~~ the at least a portion of ~~said~~ the surface of ~~said~~ the bare semiconductor die when the radiation-curable components are in a cured state.

21. (Currently Amended) The tape of claim 20, wherein ~~said curing of said first outermost adhesive layer provides a loss of adhesion between said first outermost adhesive layer and said second adhesive layer~~ the tape comprises a first bond strength between the film material and the at least a portion of the surface of the bare semiconductor die when the electromagnetic radiation-curable components are in an uncured state, and a second bond strength between the film material and the first outermost adhesive layer when the electromagnetic radiation-curable components are in a cured state, the second bond strength being lower than the first bond strength.

22. (Currently Amended) The tape of claim 20, wherein ~~said curing of said first outermost adhesive layer forms~~ the electromagnetic radiation-curable components form a substantially homogenous surface upon exposure to an electromagnetic radiation source, the substantially homogenous surface being disposed over ~~said~~ the at least ~~said~~ the portion of ~~said~~ the surface of a bare semiconductor die, the substantially homogenous surface being suitable for laser marking for forming a mark on ~~said~~ the surface of ~~said~~ the bare semiconductor die.

23. (Currently Amended) The tape of claim 19, wherein ~~said~~ the second adhesive layer ~~includes a layer cured by exposure to~~ comprises electromagnetic radiation-curable components.

24. (Currently Amended) The tape of claim 17, wherein ~~said~~ the film material comprises a film material having translucent properties.

IN THE DRAWINGS:

The attached drawing sheet includes changes to FIG. 5. This sheet replaces the previous drawing sheet that included FIG. 5.